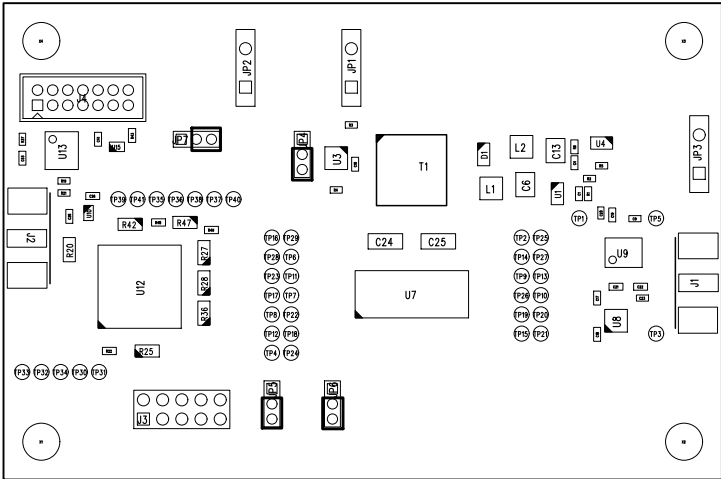


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
D00398	1	1st Prototype	E Benedict	15 Nov 16

NOTES: UNLESS OTHERWISE SPECIFIED

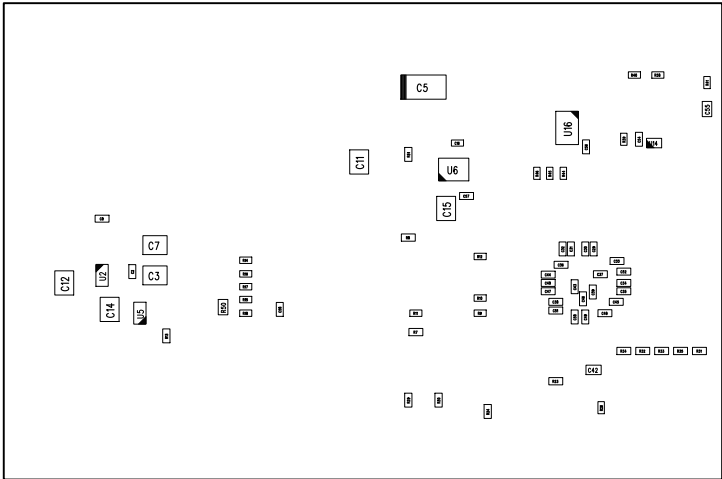
1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. MAXIMUM SOLDER TEMPERATURE IS 250 DEG C.
3. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.  
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.  
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
6. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE  
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
7. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD




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APPROVALS		 <div>1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1600 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY</div>		
PCB DES.	EB			
APP ENG.	EB	TITLE: BOTTOM ASSEMBLY DEMO CIRCUIT 100MHz DAC - SPI SERIAL INTERFACE		
		SIZE N/A	IC NO. LTM2895IY DEMO CIRCUIT DC2589A	REV. 1
SCALE = NONE		SHT 2 OF 2		